

## FEATURES

- | Size Design  $\Phi 8.0 \times 10.0\text{mm}$

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- | High Current Handling Capability 20,000A @ 8/20  $\mu\text{s}$

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- | Low Capacitance and Insertion Loss

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- | Quick Response and Long Service Life

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- | Moisture sensitivity level: Level 1

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$\Phi 8.0 \times 10.0\text{mm}$

## APPLICATION INFORMATION

- | Communication equipment.

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- | Repeaters, Modems

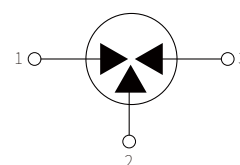
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- | Telephone Interface, Line cards.

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- | Data communication equipment.

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Schematic Symbol

## AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	UL Certificated E505857

## PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

## ELECTRICAL PARAMETER

Parameter	Symbol	Rating	Unit
DC Blocking Voltage 1)	100V/s	53-98	V
Impulse Spark-over Voltage	At 1kV/ $\mu$ s	for 99 % of measured values $\leq 600$	V
	At 1kV/ $\mu$ s	Typical values of distribution $\leq 550$	V
Impulse Discharge Current 2)	8/20 $\mu$ s	20	KA
Insulation Resistance	DC=50V	$\geq 1$	G $\Omega$
Capacitance at 1MHz	$V_{DC}=0.5V$	$\leq 2$	pF
Operating and Storage Temperature		-40~125	$^{\circ}C$

1) In ionized mode

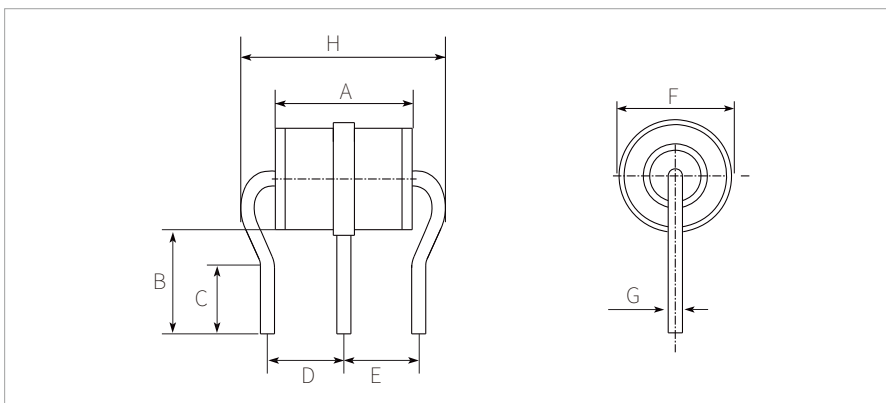
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IIEC 61643-311

## ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85 $^{\circ}C$ ; Time:2H
Low Temperature Storage Test	Temperature: -40 $^{\circ}C$ ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260 $^{\circ}C$ ; Time of dip soldering: 10s,1time

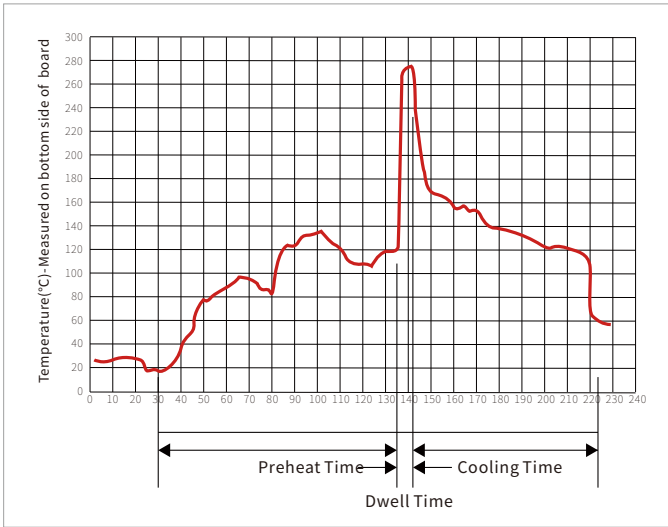
**NOTE:**Up-screen program can be specified by customer' s request via contacting Semiware service

## PRODUCT DIMENSIONS




Ref.	Outline Dimensions
	Millimeters
A	10 $\pm$ 0.3
B	7.0 $\pm$ 0.5
C	4.0 $\pm$ 0.5
D	4.4 $\pm$ 0.3
E	4.4 $\pm$ 0.3
F	$\Phi$ 8.0 $\pm$ 0.2
G	$\Phi$ 1.0
H	13 $\pm$ 1

## WAVE SOLDERING



Wave Parameter		Lead-free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time(min to max)	60 – 180 secs
Solder pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds

## ORDERING INFORMATION

Part Number	Size	Marking	Qty/pcs		
			Tray	Inner Box	Carton
SG3R08B070	Φ8.0*10.0mm	 SG070 08	100	500	6000

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**By QR Code**

Website



Wechat

To find your local partner within Semiware' s global network: [www.semiware.com](http://www.semiware.com)

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